

**REVISION M**

DO NOT SCALE FROM THIS PRINT

| EDGE MOUNT THICKNESS | "A"        | "B"          | "C"        | BODY               | CONTACT       |
|----------------------|------------|--------------|------------|--------------------|---------------|
| -EM2                 | .130[3.30] | .0670[1.702] | .058[1.47] | QTS-25-01-D-EM2-XX | T-1S42-01-XXX |
| *-EM3                | .160[4.06] | .0980[2.489] | .088[2.24] | QTS-25-01-D-EM3-XX | T-1S42-02-XXX |

\* = SEE NOTE 11

**QTS-XXX-01-XXX-D-EMX-XX**

No OF POSITIONS  
-025, -050, -075,  
\*\*-100, \*\*-125  
(PER ROW)  
\*\*SEE NOTE 12

OPTION  
-TY: TRAY PACKAGING

LEAD STYLE  
-01: .1680[4.267]

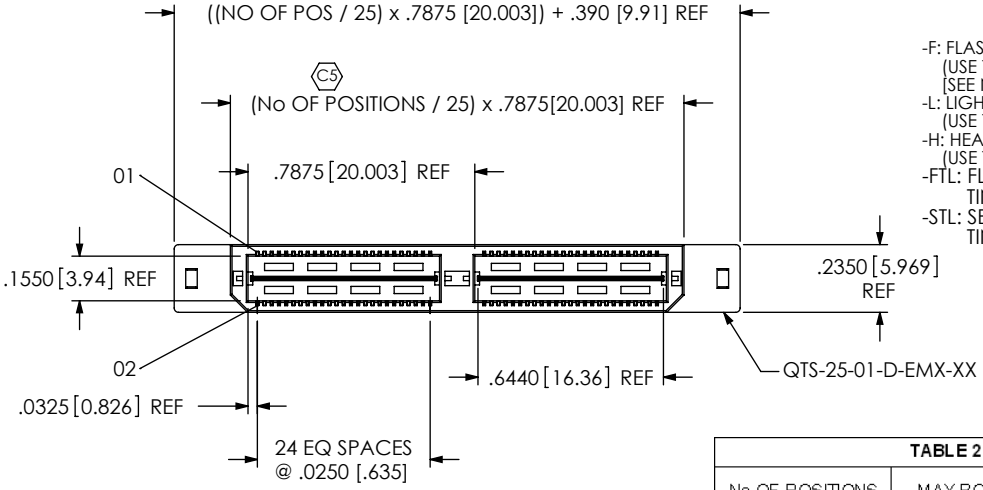
EDGE MOUNT THICKNESS  
-EM2: .064[1.63] +/- .004 PCB  
(USE QTS-25-01-D-EM2-XX & T-1S42-01-XXX)

-EM3:  
(USE QTS-25-01-D-EM3-XX & T-1S42-02-XXX)  
**SEE NOTE 11**

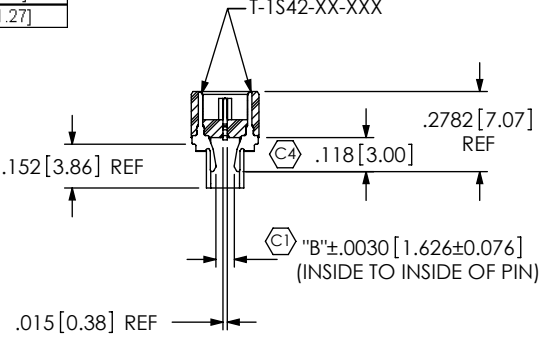
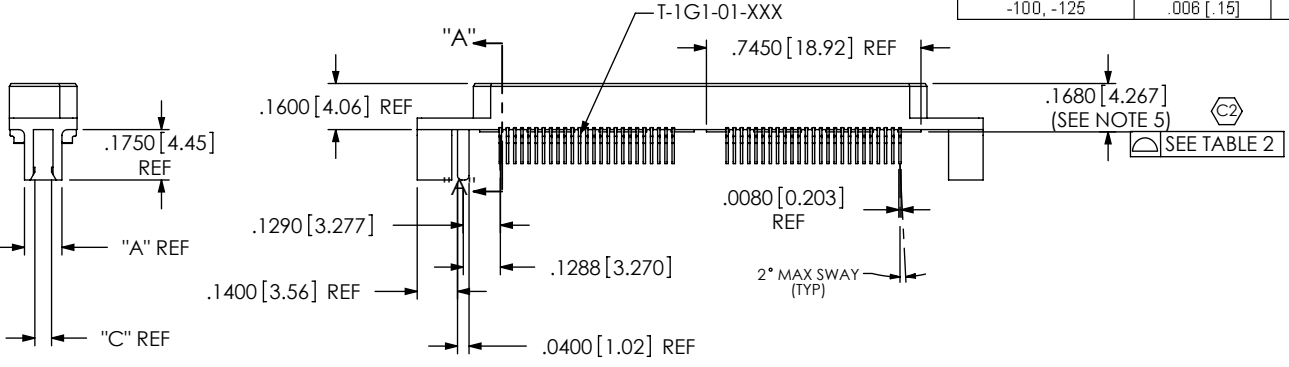
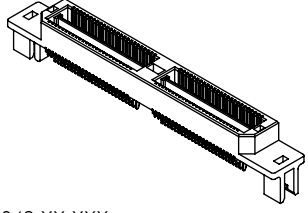
**PLATING SPECIFICATION**

- F: FLASH SELECTIVE GOLD WITH MATTE TIN TAILS (USE T-1S42-XX-F & T-1G1-01-F) [SEE NOTE 7]
- L: LIGHT SELECTIVE GOLD WITH MATTE TIN TAILS (USE T-1S42-XX-L & T-1G1-01-L)
- H: HEAVY GOLD (USE T-1S42-XX-H & T-1G1-01-G)
- FTL: FLASH SELECTIVE GOLD, TIN/LEAD TAIL (USE T-1S42-XX-FTL & T-1G1-01-FTL)
- STL: SELECTIVE GOLD, TIN/LEAD TAIL (USE T-1S42-XX-STL & T-1G1-01-STL)

ROW SPECIFICATION  
-D: DOUBLE (USE QTS-25-XX-D-EMX-XX)  
No OF BANKS



| No OF POSITIONS  | MAX BOW    | GND PLANE COPLANARITY |
|------------------|------------|-----------------------|
| -025, -050, -075 | .004 [.10] | .004 [.10]            |
| -100, -125       | .006 [.15] | .005 [1.27]           |



**SECTION "A"- "A"**

- NOTES:
1. (C) REPRESENTS A CRITICAL DIMENSION.
  2. BURR ALLOWANCE: .0015 [.038] MAX.
  3. MINIMUM PUSHOUT FORCE: 6 OZ.
  4. MINIMUM GROUND PLANE RETENTION: 1 LB.
  5. MAXIMUM VARIANCE: .002 [.05].
  6. PARTS TO BE MOLDED TO POSITION.
  7. -L PLATING CAN BE SUBSTITUTED FOR -F PLATING (TERMINAL).
  8. NOTE DELETED.
  9. BOARD THICKNESS TO BE MEASURED FROM SOLDER PAD TO SOLDER PAD.
  10. SEE [www.samtec.com/processing/edgemt\\_tectalk/index.htm](http://www.samtec.com/processing/edgemt_tectalk/index.htm) FOR PROCESSING EDGE MOUNT PARTS TO BOARD.
  11. -EM3 IS NOT A STANDARD OFFERING; AVAILABLE AS AN ASP ONLY. PLEASE CONTACT SAMTEC INTERCONNECT PROCESSING GROUP WITH ORDER INQUIRIES
  12. FOR NEW APPLICATIONS REQUIRING THESE POSITIONS, PLEASE CONTACT SAMTEC INTERCONNECT PROCESSING GROUP.
  13. PARTS WITHOUT -TY OPTION SHALL BE PACKAGED IN TRAYS.

UNLESS OTHERWISE SPECIFIED, DIMENSIONS ARE IN INCHES. TOLERANCES ARE:  
DECIMALS ANGLES  
.XX: ±.01 [.3]  
.XXX: ±.005 [.13]  
.XXXX: ±.0020 [.051]

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**MATERIAL:** DO NOT SCALE DRAWING SHEET SCALE: 1.5:1  
INSULATOR: LCP, COLOR: BLACK  
TERMINAL: PHOS BRONZE  
GROUND PLANE: PHOS BRONZE

DESCRIPTION: .635mm EDGE MOUNT HS TERMINAL ASSEMBLY

DWG. NO. **QTS-XXX-01-XXX-D-EMX-XX**

BY: DEAN P 4/24/2000 SHEET 1 OF 1